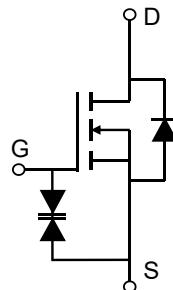


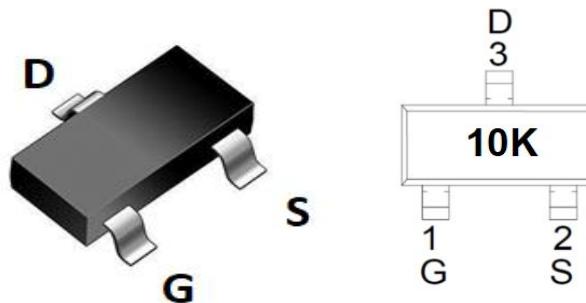
Description

Features

- 30V, 0.7A
- $R_{DS(ON)}$ Typ = 213mΩ @ V_{GS} = 4.5V
- $R_{DS(ON)}$ Typ = 252mΩ @ V_{GS} = 2.5V
- $R_{DS(ON)}$ Typ = 343mΩ @ V_{GS} = 1.8V
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free
- ESD Protected: 2KV



Schematic Diagram



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMLCTU03210K	10K	SOT-523-3L	TAPING	7"	3000	120000

Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	30	V
V_{GS}	Gate-to-Source Voltage	± 10	V
I_D	Continuous Drain Current $T_A = 25^\circ\text{C}$	0.7	A
		$T_A = 100^\circ\text{C}$	A
I_{DM}	Pulsed Drain Current ⁽¹⁾	2.8	A
P_D	Power Dissipation $T_A = 25^\circ\text{C}$	0.23	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽²⁾	540	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 30V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±10V	-	-	±10	μA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	0.4	0.65	0.9	V
		V _{GS} = 4.5V, I _D = 0.3A	-	213	256	mΩ
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 2.5V, I _D = 0.3A	-	252	302	mΩ
		V _{GS} = 1.8V, I _D = 0.1A	-	343	410	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance		-	54	-	pF
C _{oss}	Output Capacitance	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz	-	11	-	pF
C _{rss}	Reverse Transfer Capacitance		-	5	-	pF
Q _g	Total Gate Charge		-	1.4	-	nC
Q _{gs}	Gate Source Charge	V _{GS} = 0 to 10V V _{DS} = 10V, I _D = 0.4A	-	0.15	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	0.25	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime		-	12	-	ns
t _r	Turn-On Rise Time	V _{GS} = 10V, V _{DD} = 10V	-	8	-	ns
t _{d(off)}	Turn-Off DelayTime	I _D = 0.4A, R _{GEN} = 3Ω	-	65	-	ns
t _f	Turn-Off Fall Time		-	28	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	0.7	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	2.8	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 0.3A	-	-	1.2	V

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. R_{θJA} is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

Test Circuit

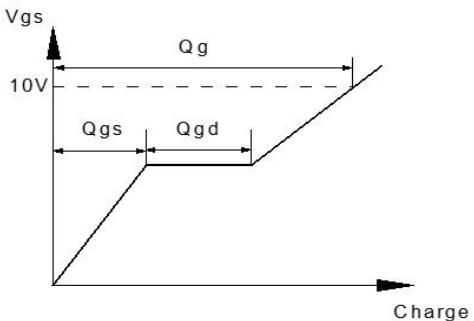
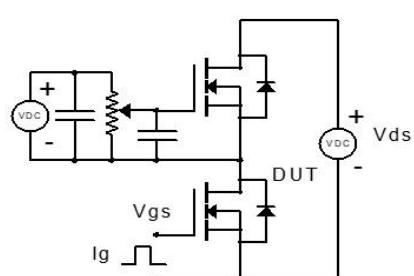


Figure 1: Gate Charge Test Circuit & Waveform

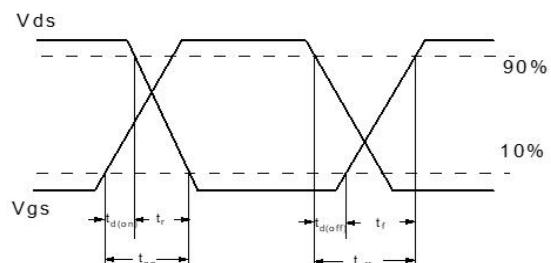
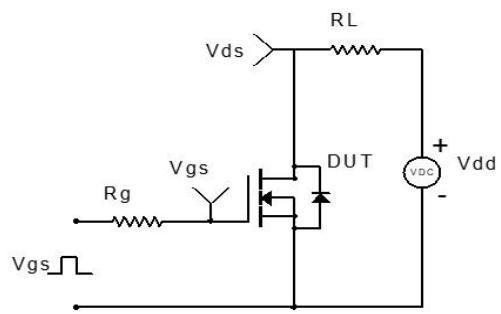


Figure 2: Resistive Switching Test Circuit & Waveform

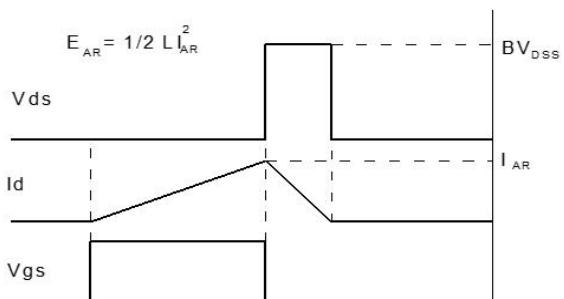
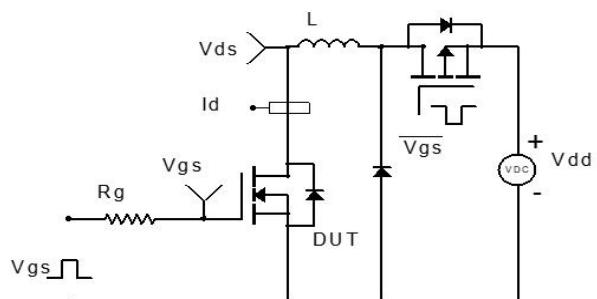


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

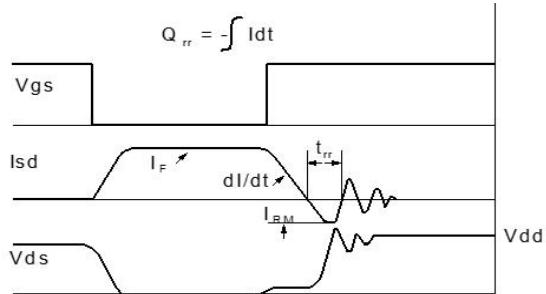
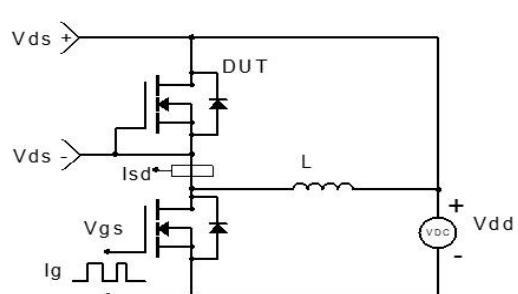
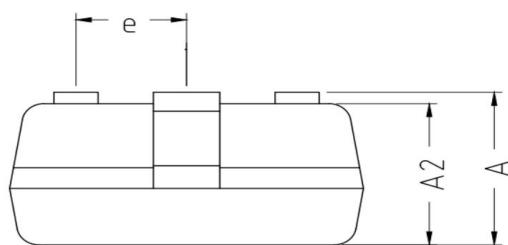
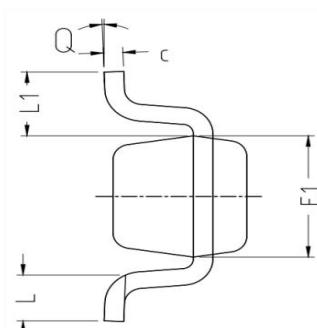
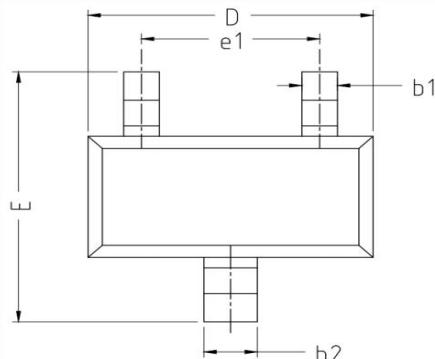


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(SOT-523-3L)



PKG	COMMON IN DIMENSION (MM)		
	SOT-523-3L		
Symbol	MIN	NOM	MAX
A	0.700	0.800	0.900
A2	0.700	0.750	0.800
b1	0.150	0.200	0.250
b2	0.250	0.300	0.350
c	0.100	0.130	0.200
D	1.550	1.600	1.700
E	1.450	1.600	1.750
E1	0.700	0.800	0.900
e	0.500 TYP		
e1	0.900	1.000	1.100
L	0.260	0.360	0.460
L1	0.400REF		
Q	0°	4°	8°

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